

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Art Unit :
Examiner :
Serial No. :
Filed :
Inventors :
Title :

Herewith

Soichi Ishibashi

Tetsuyuki Kyono

MOLDING MATERIAL AND Docket: 1066-DIV-98

PRODUCTION PROCESS



22469

PATENT TRADEMARK OFFICE

Dated: September 18, 2001

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PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, DC 20231

Sir:

Prior to action on the merits, please make the following amendments to the enclosed Substitute Specification, originally submitted in the parent application to the Patent Office on July 11, 2000, which incorporated all the changes made to the specification during prosecution of the parent patent application:

Version with Markings to Show Changes Made to the Claims

Please delete Claims 1-29 and 40-45 without prejudice and without disclaimer of the subject matter contained therein.

Please add the following new claim:

46. (New) A method of making a polymeric composite of a fiber bundle A that has interstices between individual fibers of said bundle A, reinforced by a multiplicity of said fibers in a dispersed condition, and said composite being adapted to be molded into a useful shape,

said method comprising the steps of:

(a) dispersing the fibers of the bundle A by pressing a thermoplastic polymer or oligomer B with a force sufficient to impregnate said fibers with said polymer or oligomer B and substantially fill said interstices with said polymer or oligomer B, while expelling any

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